# Switch-mode Power Rectifier 100 V, 40 A



# **ON Semiconductor®**





## ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 6 of this data sheet.

## Features and Benefits

- Low Forward Voltage: 0.67 V @ 125°C
- Low Power Loss/High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 40 A Total (20 A Per Diode Leg)
- Guard-Ring for Stress Protection
- NRVBB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant
- MBR41H100CTH and MBRB41H100CT-1H are Halide-Free

### Applications

- Power Supply Output Rectification
- Power Management
- Instrumentation

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight (Approximately): 1.9 Grams (TO-220)
  - 1.7 Grams (D<sup>2</sup>PAK)

1.5 Grams (TO-262)

- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

#### MAXIMUM RATINGS (Per Diode Leg)

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100	V
Average Rectified Forward Current (Rated $V_R$ ) $T_C$ = 150°C	I <sub>F(AV)</sub>	20	А
Peak Repetitive Forward Current (Rated V <sub>R</sub> , Square Wave, 20 kHz) T <sub>C</sub> = 145°C	I <sub>FRM</sub>	40	А
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)	I <sub>FSM</sub>	350	А
Operating Junction Temperature (Note 1)	TJ	+175	°C
Storage Temperature	T <sub>stg</sub>	-65 to +175	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs
Controlled Avalanche Energy (see test conditions in Figures 10 and 11)	W <sub>AVAL</sub>	400	mJ
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

## THERMAL CHARACTERISTICS (Per Diode Leg)

Characteristic	Symbol	Value	Unit
Maximum Thermal Resistance Junction-to-Case Junction-to-Ambient	${\sf R}_{ heta {\sf JC}} \ {\sf R}_{ heta {\sf JA}}$	2.0 70	°C/W

#### ELECTRICAL CHARACTERISTICS (Per Diode Leg)

Characteristic	Symbol	Value	Unit
$\begin{array}{l} \mbox{Maximum Instantaneous Forward Voltage (Note 2)} \\ (I_F = 20 \mbox{ A}, T_C = 25^{\circ}\mbox{C}) \\ (I_F = 20 \mbox{ A}, T_C = 125^{\circ}\mbox{C}) \\ (I_F = 40 \mbox{ A}, T_C = 25^{\circ}\mbox{C}) \\ (I_F = 40 \mbox{ A}, T_C = 125^{\circ}\mbox{C}) \end{array}$	VF	0.80 0.67 0.90 0.76	V
Maximum Instantaneous Reverse Current (Note 2) (Rated DC Voltage, $T_C = 125^{\circ}C$ ) (Rated DC Voltage, $T_C = 25^{\circ}C$ )	i <sub>R</sub>	10 0.01	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. 2. Pulse Test: Pulse Width =  $300 \ \mu$ s, Duty Cycle  $\leq 2.0\%$ .









Figure 8. Thermal Response Junction-to-Ambient



Figure 9. Thermal Response Junction-to-Case



Figure 10. Test Circuit

The unclamped inductive switching circuit shown in Figure 10 was used to demonstrate the controlled avalanche capability of this device. A mercury switch was used instead of an electronic switch to simulate a noisy environment when the switch was being opened.

When  $S_1$  is closed at  $t_0$  the current in the inductor  $I_L$  ramps up linearly; and energy is stored in the coil. At  $t_1$  the switch is opened and the voltage across the diode under test begins to rise rapidly, due to di/dt effects, when this induced voltage reaches the breakdown voltage of the diode, it is clamped at  $BV_{DUT}$  and the diode begins to conduct the full load current which now starts to decay linearly through the diode, and goes to zero at  $t_2$ .

By solving the loop equation at the point in time when  $S_1$  is opened; and calculating the energy that is transferred to the diode it can be shown that the total energy transferred is equal to the energy stored in the inductor plus a finite amount of energy from the V<sub>DD</sub> power supply while the diode is in breakdown (from  $t_1$  to  $t_2$ ) minus any losses due to finite component resistances. Assuming the component resistive



Figure 11. Current–Voltage Waveforms

elements are small Equation (1) approximates the total energy transferred to the diode. It can be seen from this equation that if the  $V_{DD}$  voltage is low compared to the breakdown voltage of the device, the amount of energy contributed by the supply during breakdown is small and the total energy can be assumed to be nearly equal to the energy stored in the coil during the time when S<sub>1</sub> was closed, Equation (2).

**EQUATION (1):** 

$$W_{AVAL} \approx \frac{1}{2} LI_{LPK}^{2} \left( \frac{BV_{DUT}}{BV_{DUT}V_{DD}} \right)$$

EQUATION (2):

$$W_{AVAL} \approx \frac{1}{2} LI_{LPK}^2$$

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>	
MBR41H100CTG	TO-220 (Pb-Free)	50 Units / Rail	
MBR41H100CTH	TO-220 (Halide-Free)	50 Units / Rail	
MBRB41H100CT-1G	I <sup>2</sup> PAK (Pb–Free)	50 Units / Rail	
MBRB41H100CT-1H (In Development)	I <sup>2</sup> PAK (Halide–Free)	50 Units / Rail	
MBRB41H100CTT4G	D <sup>2</sup> PAK 3 (Pb–Free)	800 Units / Tape & Reel	
NRVBB41H100CTT4G*	D <sup>2</sup> PAK 3 (Pb–Free)	800 Units / Tape & Reel	

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. \*NRVBB Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q100 Qualified and

PPAP Capable.

## PACKAGE DIMENSIONS

TO-220 CASE 221A-09 **ISSUE AH** 



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIN	IETERS
DIM	MIN	I MAX MIN N		MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.415	9.66	10.53
С	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
н	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
Κ	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
۷	0.045		1.15	
Ζ		0.080		2.04

STYLE 6: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

## PACKAGE DIMENSIONS



NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. 418B–01 THRU 418B–03 OBSOLETE, NEW STANDARD 418B–04.

	INCHES		INCHES MILLIMETE	
DIM	MIN	MAX	MIN	MAX
Α	0.340	0.380	8.64	9.65
В	0.380	0.405	9.65	10.29
С	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
Е	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
κ	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
Μ	0.280	0.320	7.11	8.13
Ν	0.197 REF		5.00 REF	
Ρ	0.079 REF		2.00 REF	
R	0.039	0.039 REF		REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

STYLE 3: PIN 1. ANODE 2. CATHODE 3. ANODE 4. CATHODE

\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DIMENSIONS: MILLIMETERS

5.080 PITCH

1.016

#### PACKAGE DIMENSIONS

I<sup>2</sup>PAK (TO-262) CASE 418D ISSUE D



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